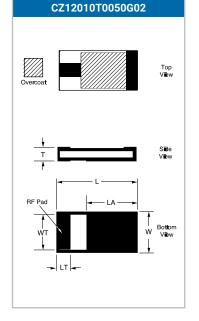
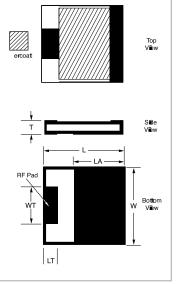
Surface Mount Chip Terminations CZ1 Style

GENERAL SPECIFICATIONS

- Nominal Impedance: 50 Ω
- Resistive Tolerance: ±2% standard
- Operating Temp Range: -55 to +150°C
- Temperature Coefficient: ±150 ppm/°C
- · Resistive Elements: Tantalum, Thin Film Processed
- Substrate Material: Aluminum Nitride
- Terminals: Silver over Nickel
- · Lead-Free, RoHS Compliant
- Reliability: MIL-PRF-55342
- Tape & Reel Specifications:



CZ12010T0050G &



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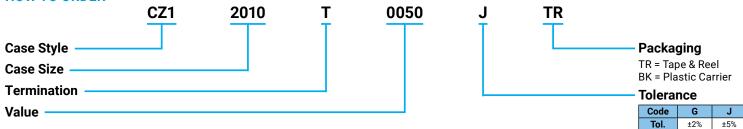
CZ12525T0050G

Values in Inches

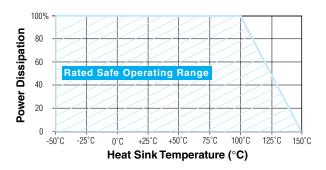
Part Number	W ±.010	L ±.010	T ±.005	LT ±.005	WT ±.005	LA ±.005	Frequency Range (GHz)	VSWR (Typ.)	Power Max* (Watts)
CZ12010T0050G	.100	.200	.040	.040	.090	.115	DC - 3.0	1.20:1	10W
CZ12010T0050G02	.100	.200	.040	.020	.090	.140	DC - 3.0	1.20:1	10W
CZ12525T0050G	.245	.245	.040	.030	.125	.170	DC - 4.0	1.25:1	20W

* Test Condition: Chip soldered to a via patch on a 30-mil-thick Rogers R04350 board; Land surfaces at 100° C; maximum rated power applied. Specification: The resistance of the film shall change no more than 0.5% during and after a 1000-hr. Burn-in per Mil-PRF-55342.

HOW TO ORDER



POWER DERATING

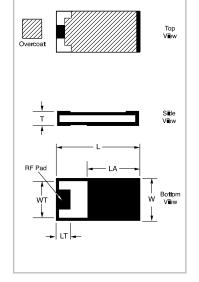


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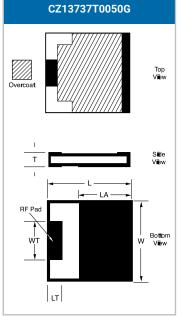
Surface Mount Chip Terminations CZ1 Style

GENERAL SPECIFICATIONS

- Nominal Impedance: 50 Ω
- Resistive Tolerance: ±2% standard
- Operating Temp Range: -55 to +150°C
- Temperature Coefficient: ±150 ppm/°C
- · Resistive Elements: Tantalum, Thin Film Processed
- Substrate Material: Aluminum Nitride
- Terminals: Silver over Nickel
- Lead-Free, RoHS Compliant
- Reliability: MIL-PRF-55342
- Tape & Reel Specifications:



CZ13725T0050G



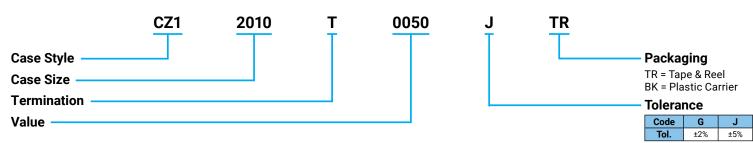
Values in Inches

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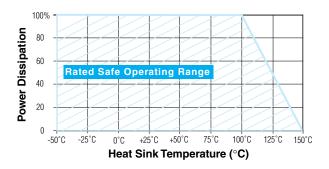
Part Number	W ±.010	L ±.010	T ±.005	LT ±.005	WT ±.005	LA ±.005	Frequency Range (GHz)	VSWR (Typ.)	Power Max* (Watts)
CZ13725T0050G	.250	.375	.040	.050	.125	.260	DC - 2.2	1.20:1	30W
CZ13737T0050G	.370	.370	.040	.050	.125	.275	DC - 3.0	1.25:1	40W

* Test Condition: Chip soldered to a via patch on a 30-mil-thick Rogers R04350 board; Land surfaces at 100° C; maximum rated power applied. Specification: The resistance of the film shall change no more than 0.5% during and after a 1000-hr. Burn-in per Mil-PRF-55342.

HOW TO ORDER



POWER DERATING



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